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# A high-power inverter based on hybrid switch SiC+IGBT technology

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# Agenda

1 Efficiency increase in high power systems

2 Power technology options for inverters

3 Hybrid switch technology

4 30kW hybrid switch inverter

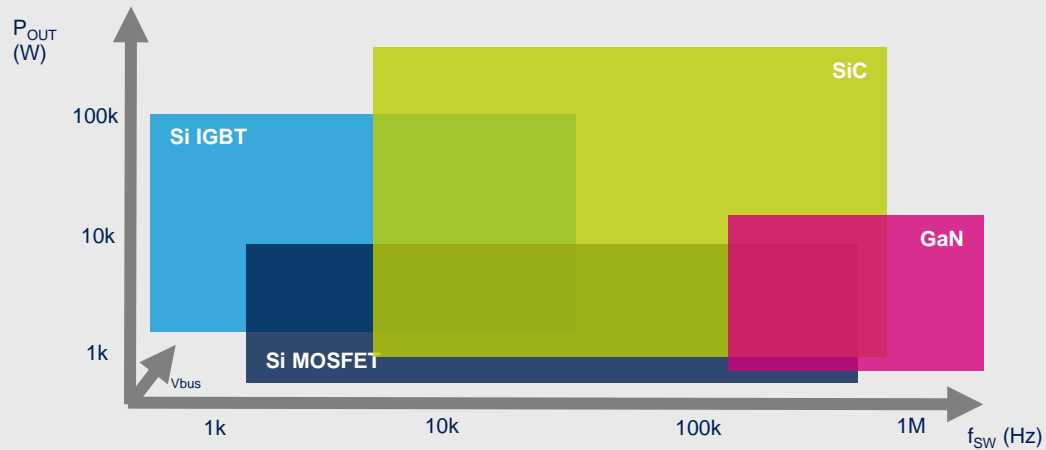
5 Summary



# Efficiency increase in high power systems

## Power systems using SiC technology

### Power technology positioning



- **Efficiency increase:** CO2 emission reduction
- **Power density:** smaller and lighter power unit form factor
- **Cost reduction:** system level cost reduction or lower TCO

### High-end industrial

- Solar inverter
- Energy storage
- Power supply
- Charging station
- Welding
- Motor drives



### Car electrification

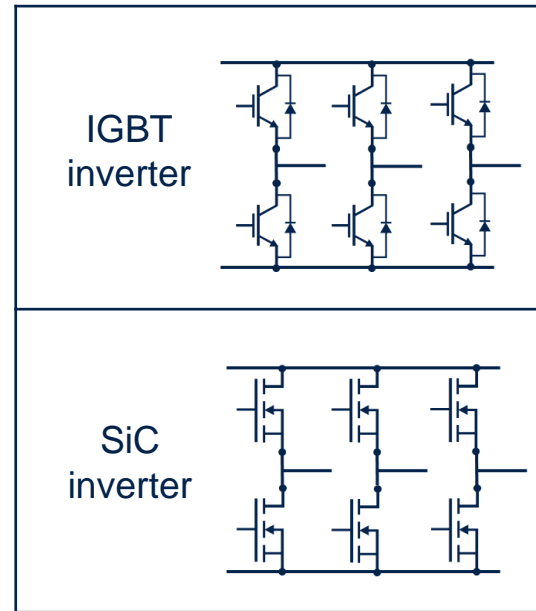
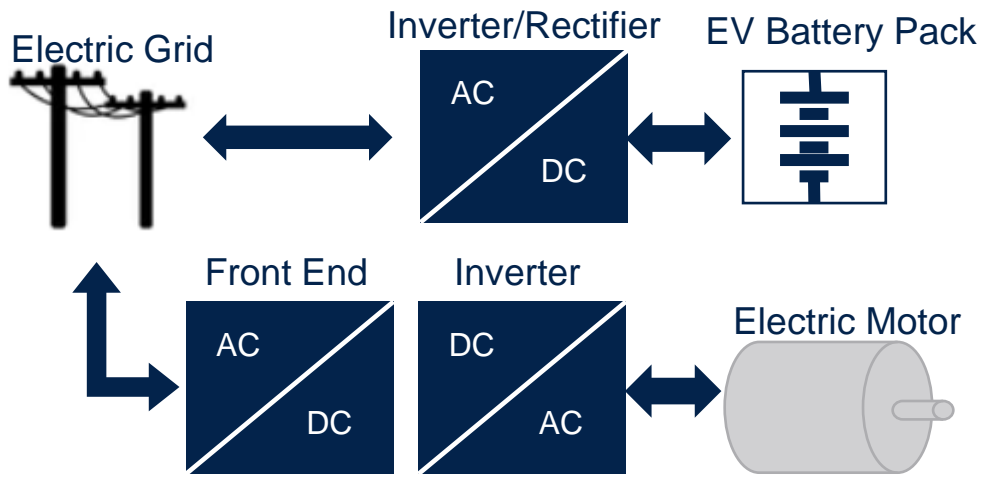
- Traction inverter
- OBC
- DC-DC converter





# Power technology options for inverter

## System level cost - TCO reduction vs efficiency increase



**Low-cost inverter**

**Higher system cost**

**High-cost inverter**

**Lower system cost**

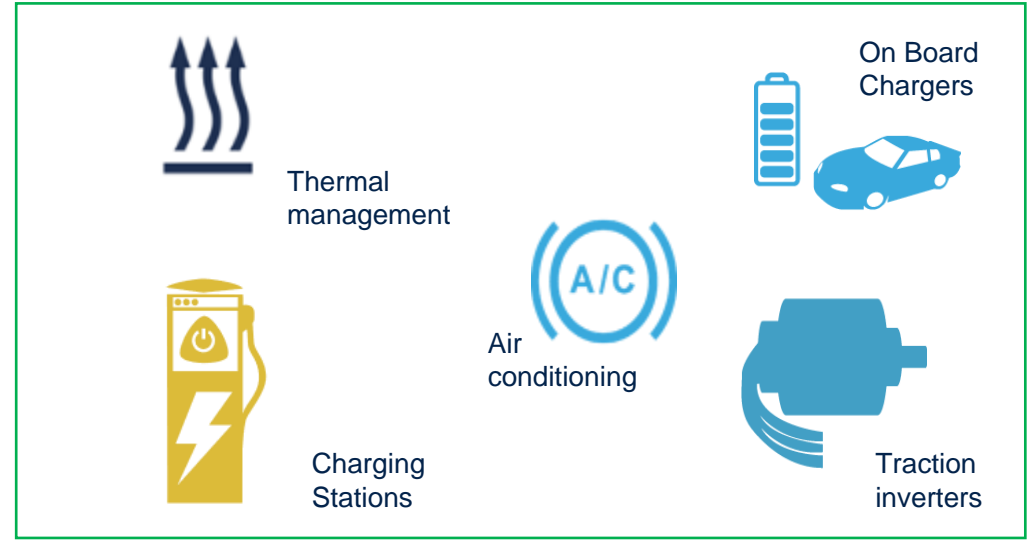
**Main high-power applications adopting SiC**

- Solar inverter
- Energy storage
- Charging station
- Motor drives
- Traction inverter



# Trench field stop IGBTs

## Solutions for every application in electric vehicles



### HIGH SWITCHING FREQUENCY CONVERSION

HYBRID Si+SiC

650V - HB series

600V- V series

STGH30H65DFB-2AG  
STGSH80HB65DAG

STGWA60V60DWFAG

### MOTOR CONTROL

650V - M series

750V - MH series

1200V - MS series

STGST200G65DFAG  
STGSB200M65DF2AG

STG320MH75FD11AG  
ES AV, MP Q1'24

GWA40MS120F4DAG  
GWA40MS120F4AG

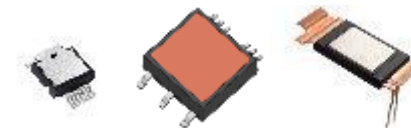
Dice



Discrete packages



Top Side cooling





# ST silicon carbide technologies

## Focus applications



## SiC key facts

In volume production since 2017 with  
 > **300 million** chips to automotive customers

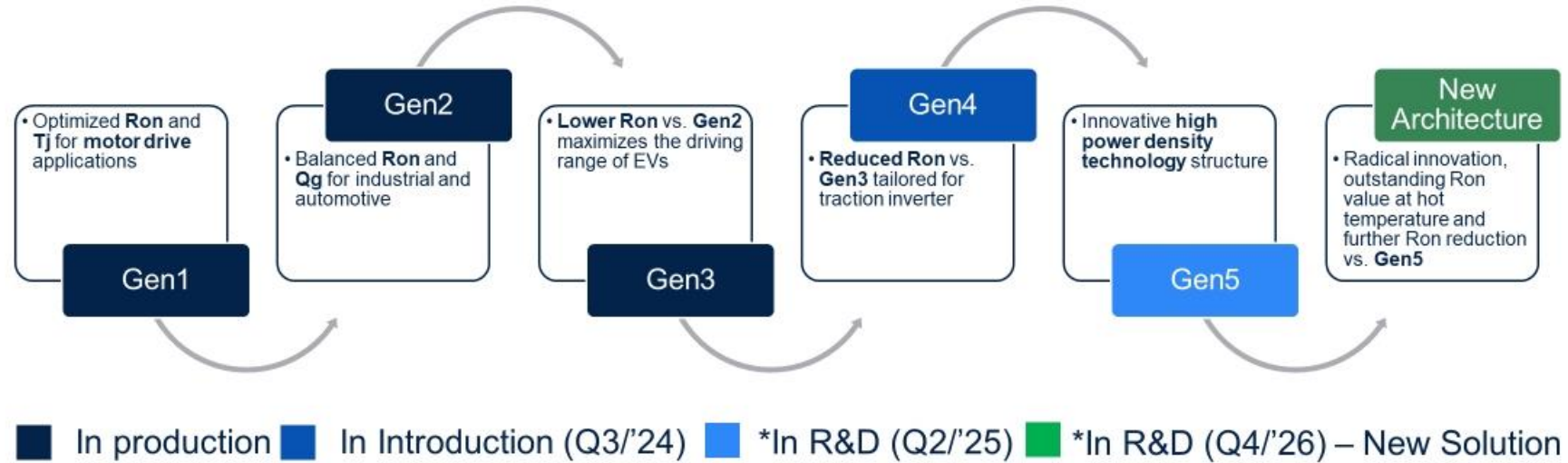
> **6M BEV** equipped



\* Technology qualification with ES available

\*\* Under development

## Product roadmap



## Advanced packaging



Bare die

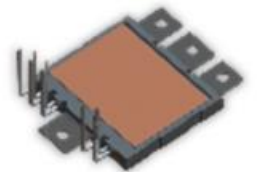


HiP247-4 leads



ACEPACK SMIT

ACEPACK DRIVE



ACEPACK DRIVE DSC\*\*



HU3PAK



STPAK



ACEPACK 1 - 2



ACEPACK DRIVE SSC\*\*



ACEPACK DRIVE DSC\*\*

# ST silicon carbide manufacturing strategy

## Device manufacturing

In volume production with 150 mm since 2017

- > 300 million chips to automotive customers
- Capacity expanded **2.4X** in 2022 vs. 2020

Further **+250%** of capacity increasing in 2027 vs. 2022

200 mm start production in Catania by 2024

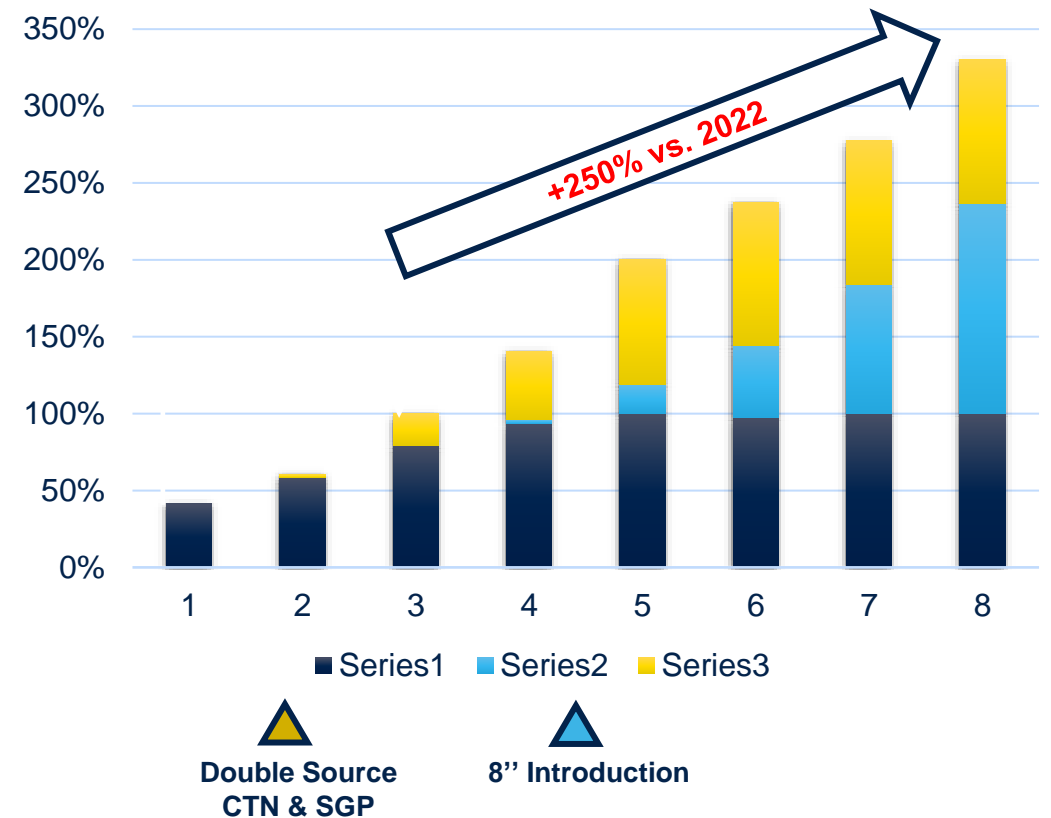
- Front-end FABs: **Catania** (Italy) and **Ang Mo Kio** (Singapore)
- Back-end FABs: **Shenzhen** (China) and **Bouskoura** (Morocco)

## Substrate manufacturing

- ST SiC\* 150 mm small volumes production in **Norrköping** (Sweden); 200 mm prototypes with good quality and yield
- New full integrated fab under construction in **Catania**, ready by 2024 and targeting > 40% of substrate internal needs by 2025

\* Norstel AB renamed as ST SiC AB in 2020

## SiC normalized capacity evolution (2022)



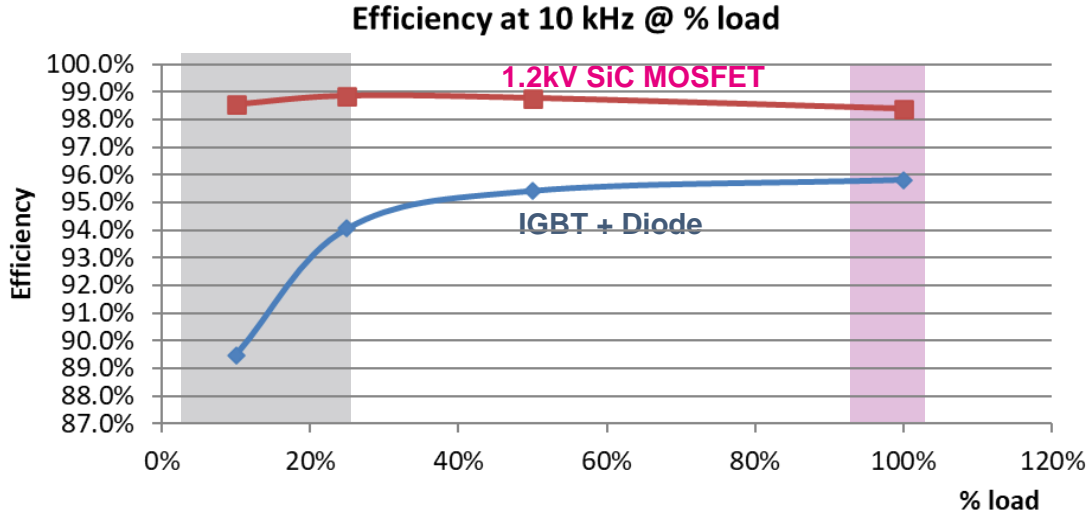
# Example of SiC MOSFET impact on high power inverter

## 1200V SiC MOSFET vs. IGBT: 210 kW inverter @ 10 kHz

Typ. power losses per switch @ 350 A <sub>rms</sub> peak power		IGBT + Diode		1.2kV SiC MOSFET
	total chip area (mm <sup>2</sup> )	600	x5	120
	conduction losses (W)	300		307
	switching losses (W)	564	x4	143
	total losses (W)	864	x2	450
	Junction Temp (°C)	134.8		132.4

### SiC adoption

- Better power density
- Better efficiency
- Reduced cooling system

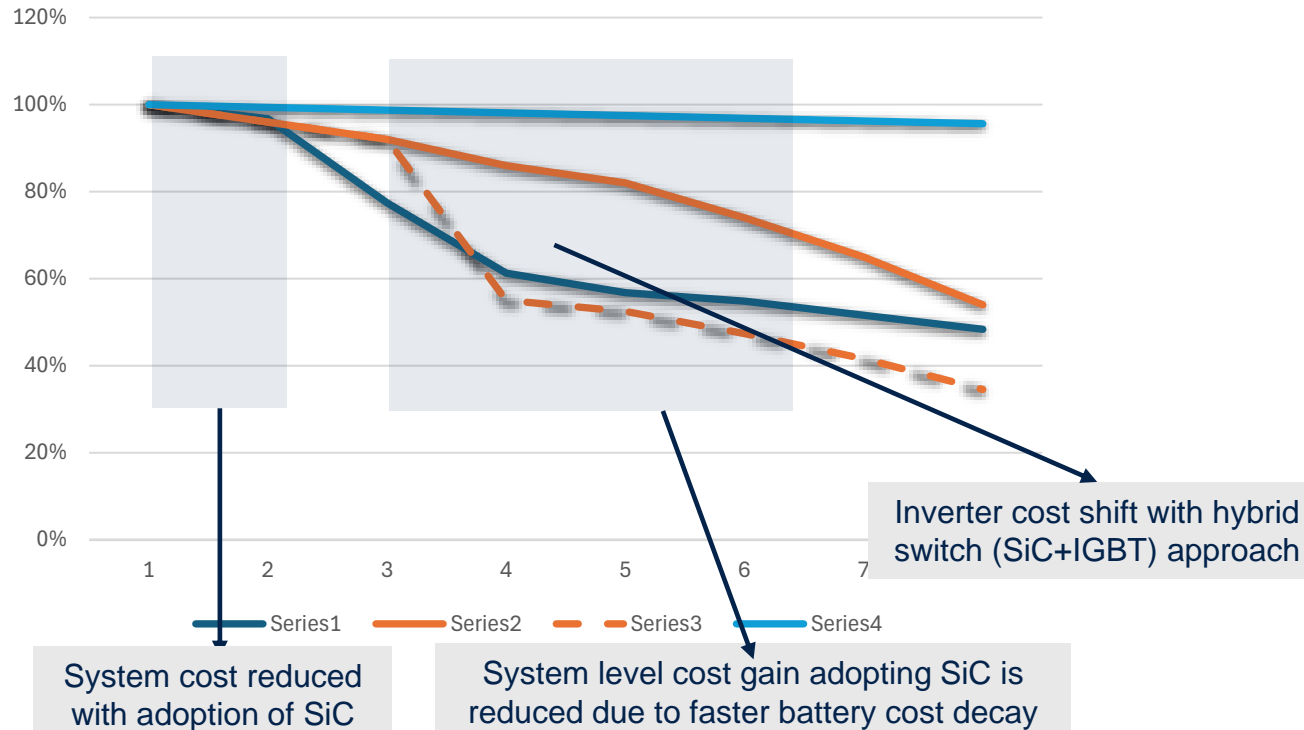




# From SiC to hybrid technology

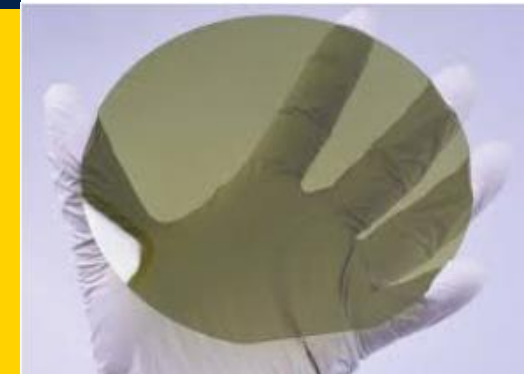
## Evolution of SiC technology cost vs battery cost

Normalized cost evolution



### SiC

- Medium-long term FAB allocation
- Yields improvement
- Die size shrinking
- Internal raw wafers
- Migration to 8" substrates



### Battery

Projections based on several publications focusing on utility-scale battery systems



[Cost Projections for Utility-Scale Battery Storage: 2023 Update \(nrel.gov\)](https://www.nrel.gov/battery/cost-projections-for-utility-scale-battery-storage-2023-update)

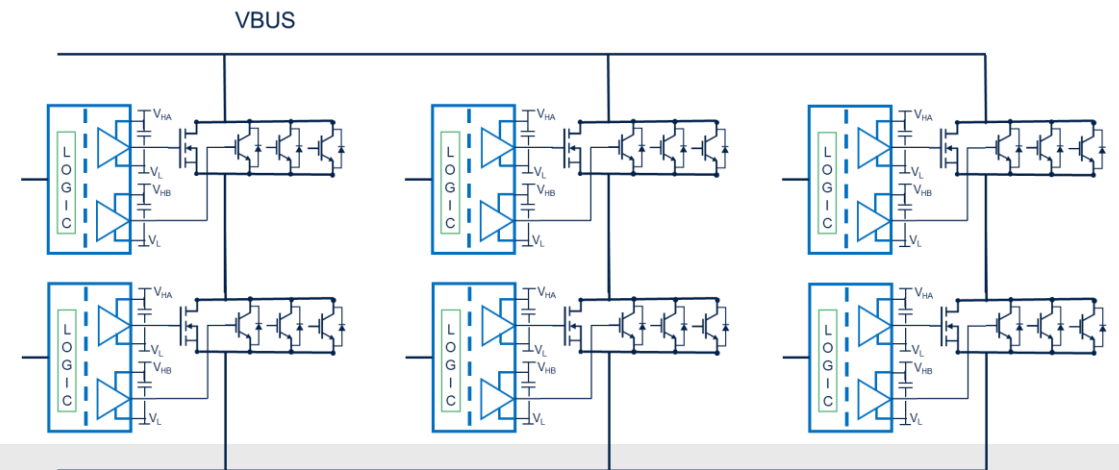
<https://www.goldmansachs.com/intelligence/pages/electric-vehicle-battery-prices-falling.html>

# Hybrid switch inverter

## Hybrid switch 4:1 (IGBTs + SiC)

### Inverter test conditions

VBUS	850	V
Vout (line to Line)	480	Vac-rms
Vout(line to neutral)	277	Vac-rms
Vout(line to neutral)	392	Vac-pk
Pout (active)	30,000	W
Power Factor	0.80	
phy	0.64	rad
Pout per phase	10000	W
Iout rms	45.11	A
Iout pk	63.79	A
Fs	10,000	Hz



### Selected devices:

- **STGW40M120DF3** Trench gate field-stop IGBT, M series 1200 V, 40 A
- **SCT070W120G3** Silicon carbide Power MOSFET 1200 V, 63 mΩ typ., 30 A in an HiP247 package

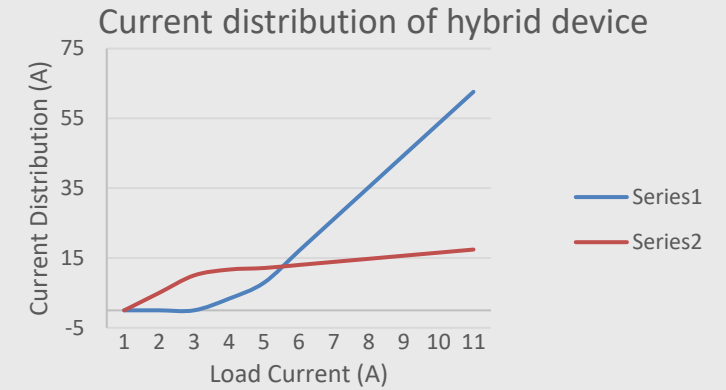
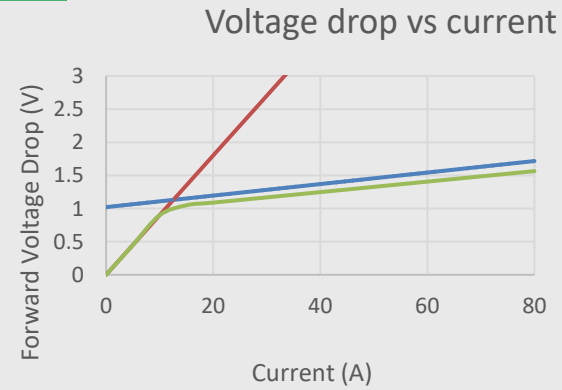
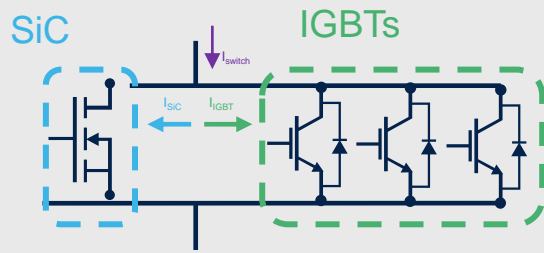
### Selection criterium

- Device with similar current rating
- SiC MOSFET able to withstand full current repetitive pulses for limited time

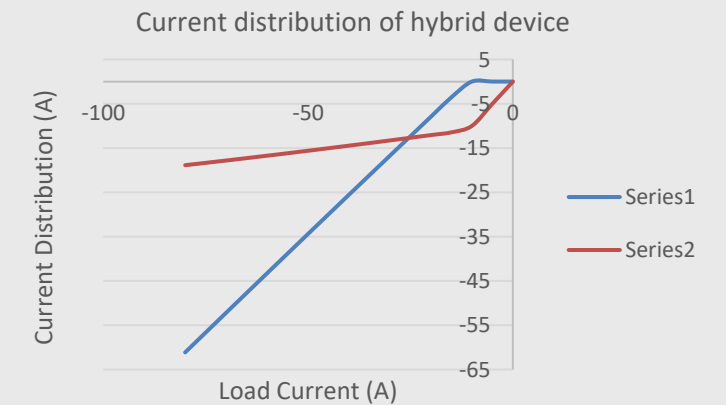
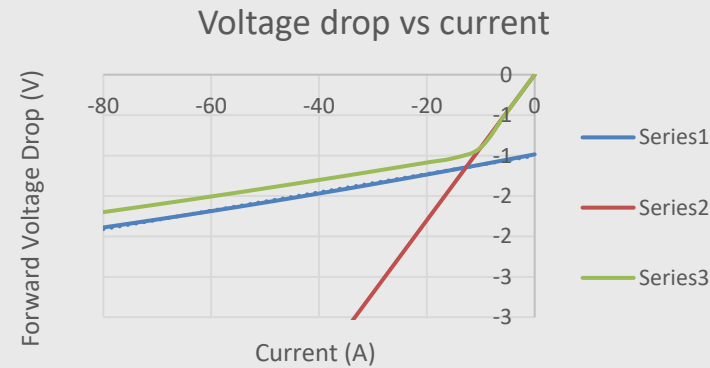
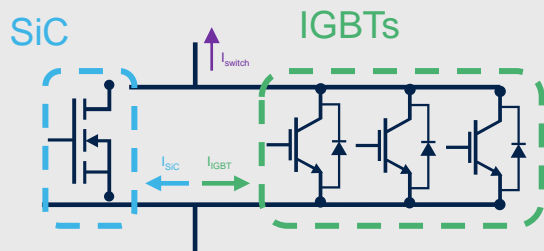


# Hybrid switch: Forward and reverse conduction

## Forward conduction losses

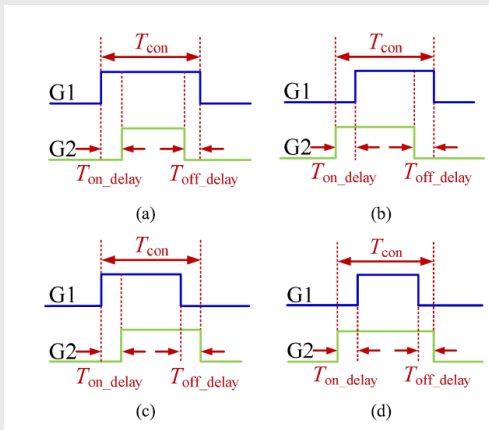


## Reverse conduction losses (freewheeling)



# Hybrid switch: Gate driving and switching operation

## Switching losses

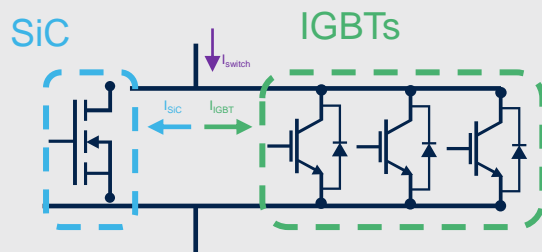


### Turn-ON

- A. (a) and (c) SiC MOSFET undertakes all forward current for a short time, and the IGBT achieves ZVS turn-on
1.  $T_{on\_delay} > T_{on\_MOS}$
  2.  $T_{on\_delay} < T_{on\_MOS}$
- B. (b) and (d) IGBTs undertakes all forward current for a short time, and the SiC achieves ZVS turn-on
1.  $T_{on\_delay} > T_{on\_IGBT}$
  2.  $T_{on\_delay} < T_{on\_IGBT}$

### Turn-OFF

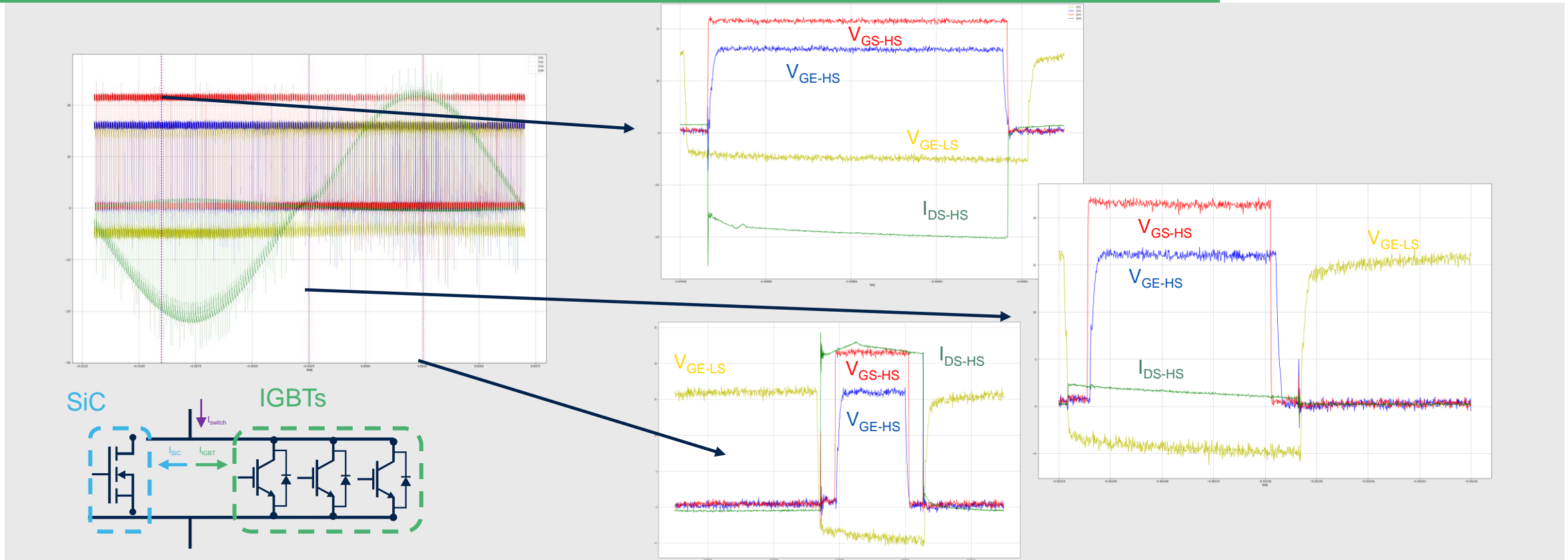
- A. (a) and (b) SiC MOSFET undertakes all forward current for a short time, and the IGBT achieves ZVS turn-off
1.  $T_{off\_delay} > T_{off\_IGBT}$
  2.  $T_{off\_delay} < T_{off\_IGBT}$
- B. (c) and (d) IGBTs undertakes all forward current for a short time, and the SiC achieves ZVS turn-off
1.  $T_{off\_delay} > T_{off\_MOS}$
  2.  $T_{off\_delay} < T_{off\_MOS}$



- IGBT gate is turned On first and  $T_{on\_delay}$  is set to synchronize commutations and avoid excessive current unbalance during the commutation
- SiC is turned off later and  $T_{off\_delay}$  is set to minimize turn-off losses (IGBT commuting in ZVS).

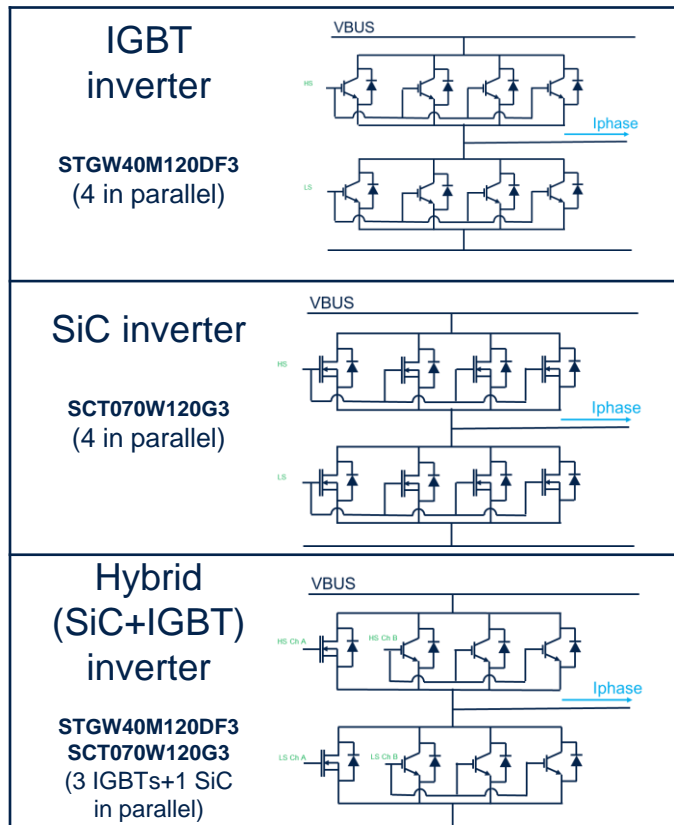
# Hybrid switch: Gate driving and switching operation

## Working waveforms

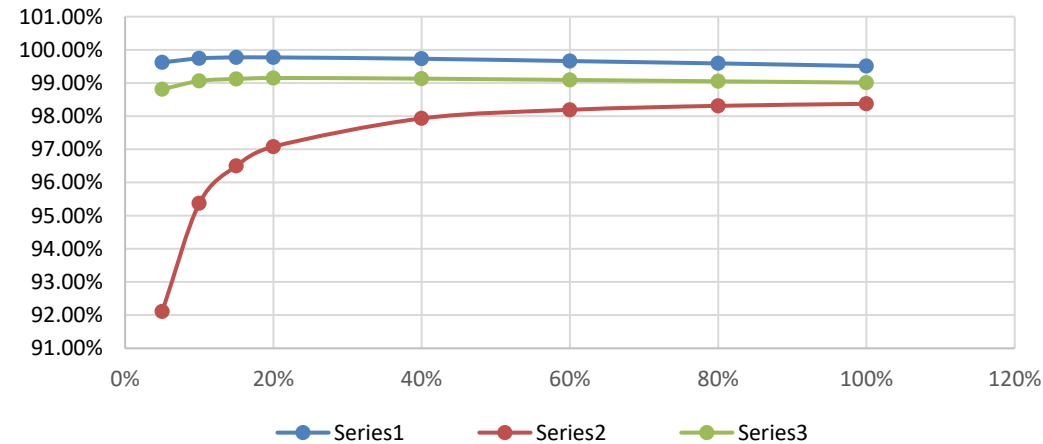


# Switch technologies vs hybrid switch in 30kW Inverter

## 1200V SiC MOSFET vs. IGBT vs hybrid: 30 kW inverter @ 10 kHz, 850V input



Efficiency comparison



Inverter specification		
VBUS	850	V
Vout (line to Line)	480	Vac-rms
Vout(line to neutral)	277	Vac-rms
Vout(line to neutral)	392	Vac-pk
Pout (active)	30,000	W
Power Factor	0.80	
phy	0.64	rad
Pout per phase	10000	W
Iout rms	45.11	A
Iout pk	63.79	A
Fs	10,000	Hz

- Hybrid switch configuration considered is 1:4 ratio (1 SiC + 3 IGBTs)
- Efficiency gain of full SiC Inverter and hybrid switch inverters vs IGBT inverter is from low load to medium load, generating advantages in power systems that operate most of the time below 40% load
- Hybrid switch inverter shows similar efficiency curve compared to SiC. Here efficiency is only 0.5% lower than SiC



# Summary



System cost benefits of SiC based inverters are evolving with battery technologies

Inverters benefit from a mix of next generation IGBTs and SiC MOSFETs

This hybrid switch optimizes inverter performance and cost

Optimized cost might enable new applications for SiC

Dedicated gate driver is required for Hybrid Switch

ST is innovating at all levels in gate drivers and power transistors to lead this new trend in inverter design

# Our technology starts with You



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